ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. international and Pa	PC, Bannockl	burn, Illinois. A	Il rights reserved nations.	under both le	his docume evel parts, th	ent is a declara he declaration	tion of the s encompasse	ubstances s all lowe	within the manuf r level materials	facturer liste	ed item. Note e manufactu	e: if the item is an a arer has engineering	assembly with low g responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Thtp://www.ipc.org/IPC-175x Distribution								laterials and	ials and Mfg Information				
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority				Resp	Response Date*				
onsemi								2024	2024-05-20					
Contact Name	tet Name Title - Contact				]	Phone - Contact*				Ema	Email - Contact*			
roduct-Env-Stewards Product Enviro Complian			ro Compliance		NA			Prod	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative			sentative		Phone - Repro	one - Representative*			Ema	Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Dat	e Version	]	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP124 R2G	CP12400CAHAB0D 2G Fixed Frequency for Flyback Conv		Current Mode Cor verters	ntroller	r 2024-05-20		(	CNW		71.87	mg	Each	
Aanufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy	J-STD-020 MSL R	Rating	Peak Pro	cess Body T	emperatu	re Max Time at	Peak Temp	erature Nu	mber of Reflow C	/cles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	se	conds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

select a RoHS exemption, if applied	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
sigma range of distribution unless	,	TT '4 . P. T.	<b>.</b>	S 1 4	C L C	E (		TT 14 63.6
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.48	mg	Supplier	Silver (Ag)	7440-22-4		0.7871	mg
			Supplier	Zinc (Zn)	7440-66-6		0.075	mg
			Supplier	Iron (Fe)	7439-89-6		0.937	mg
			Supplier	Copper (Cu)	7440-50-8		35.681	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg